



Press Release

Unisem and ASAT Limited Enter Into Cross Licensing Agreement of Key Advanced Leadless Semiconductor Packaging Technologies

Kuala Lumpur, Malaysia – July 20, 2009 – Unisem (M) Berhad today announced that it has entered into a cross licensing agreement with ASAT Limited that will allow each company to manufacture and market the other company's key advanced leadless packaging technologies. The packaging technologies included in this agreement are Unisem's Etched Leadless Package (ELP), Taped Leadframe Package (TLP) and ASAT's Thin Array Plastic Package (TAPP) and Thermal Leadless Array (TLA) package.

As the industry continues to push towards complex, yet cost effective semiconductor packaging solutions, the demand for advanced leadless leadframe based packaging continues to grow. Beyond the material cost savings over substrate based packages, design flexibility, increased I/O densities and reduced footprints have made these technologies a perfect match for smaller and thinner applications with less system board space.

"Having these packaging technologies available at both SATS providers will give our customers the added confidence of second source availability" said C.H. Ang, COO of Unisem Group. "We are excited about the opportunity to expand the availability of our package technologies as well as benefit from these additional technologies developed by ASAT", continued Ang.

"We believe that our innovative technologies allowing for higher densities in reduced footprint leadframe-based packages are well positioned, given the continued growth in the market for QFN. Our synergy with Unisem has resulted in a cooperative agreement that will help facilitate broader adoption of these technologies in a timely fashion." said Joe Martin, chief business officer of ASAT Limited.

About ASAT Limited:

ASAT Limited, a wholly owned subsidiary of ASAT Holdings Limited, is a global provider of semiconductor package design, assembly and test services. With more than 20 years of experience, the Company, through its operating subsidiary in China, ASAT Semiconductor (Dongguan) Limited, offers a definitive selection of semiconductor packages and world-class manufacturing lines. ASAT's advanced package portfolio includes standard and high thermal performance ball grid arrays, leadless plastic chip carriers, thin array plastic packages, system-in-package and flip chip. ASAT was the first company to develop moisture sensitive

level one capability on standard leaded products. Today the Company has operations in the United States, Asia and Europe. For more information, visit www.asat.com.

About Unisem

Unisem is a global provider of semiconductor assembly and test services for many of the world's most successful electronics companies. Unisem offers an integrated suite of packaging and test services such as wafer bumping, wafer probing, wafer grinding, a wide range of leadframe and substrate IC packaging, wafer level CSP and RF, analog, digital and mixed-signal test services. Our turnkey services include design, assembly, test, failure analysis, and electrical and thermal characterization. Unisem has factory locations in Ipoh, Malaysia; Wales, United Kingdom; Chengdu, People's Republic of China; Batam, Indonesia and Sunnyvale, USA. The company is headquartered in Kuala Lumpur, Malaysia. For more information about Unisem, please visit www.unisemgroup.com.

Company Contacts:

Chris Stai
Unisem Group
(408) 331-7325
cstai@unisemgroup.com

Jim Fanucchi
ASAT
(408) 404-5400
ir@asat.com

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